

**AMENDMENTS TO THE CLAIMS**

1. **(ORIGINAL)** A process for forming a conductive layer on a substrate, comprising the steps of depositing ink on the substrate by means of lithographic printing to form a seeding layer, and depositing a first electrically conducting layer on the seeding layer by electroless deposition.
2. **(ORIGINAL)** A process as claimed in claim 1, comprising the step of electroplating a second electrically conducting layer onto the first electrically conducting layer.
- 3.-18. **(CANCELED)**
19. **(PREVIOUSLY PRESENTED)** The process of claim 2 further comprising the step of attaching an electrical component to the first or second conducting layer by means of a conductive polymer adhesive.
20. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the substrate is formed from a polymer into a flexible sheet.
21. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the substrate is coated with a copolymer adhesive.
22. **(CURRENTLY AMENDED)** The process of claim 1 wherein the ink comprises a particulate material suspended in a mixture of a resin, an antioxidant, and an organic solvent.
23. **(PREVIOUSLY PRESENTED)** The process of claim 22 wherein the particulate material is a metal or carbon.

- 24. **(PREVIOUSLY PRESENTED)** The process of claim 22 wherein the resin is a polymer having amide groups.
- 25. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the thickness of the seeding layer is from 3 to 5 microns.
- 26. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the thickness of the first electrically conducting layer is less than or equal to 4 microns.
- 27. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the thickness of the first electrically conducting layer is about 0.25 microns.
- 28. **(PREVIOUSLY PRESENTED)** The process of claim 1 wherein the first electrically conducting layer is formed from at least one of copper, palladium, silver, gold, platinum, or nickel.
- 29. **(PREVIOUSLY PRESENTED)** The process of claim 1 further comprising the step of soldering an electrical component on the substrate.
- 30. **(PREVIOUSLY PRESENTED)** The process of claim 1 further comprising the step of attaching an electrical component to the first conducting layer by means of a conductive polymer adhesive.
- 31.-33. **(CANCELED)**

34. **(CURRENTLY AMENDED)** A lithographic ink for use in a lithographic printing process onto a polymer substrate, the ink comprising a metal or carbon particulate material suspended in a mixture of a resin, an antioxidant, and an organic solvent, wherein the resin comprises a polyamide.
35. **(CANCELED)**
36. **(NEW)** The lithographic ink of claim 34 wherein the ink is printed on a substrate with at least one electrically conducting layer situated thereon.
37. **(NEW)** The lithographic ink of claim 34 wherein the ink is printed on a substrate with at two or more stacked electrically conducting layers situated thereon.
38. **(NEW)** The lithographic ink of claim 34 wherein the ink is printed on a substrate with a first electrically conducting layer deposited thereon by electroless deposition.
39. **(NEW)** The lithographic ink of claim 38 wherein an electrical component is attached to the first electrically conducting layer by means of a conductive polymer adhesive.
40. **(NEW)** The lithographic ink of claim 38 wherein a second electrically conducting layer is electroplated atop the first electrically conducting layer.
41. **(NEW)** The lithographic ink of claim 38 wherein an electrical component is attached to the first or second electrically conducting layer by a conductive polymer adhesive.
42. **(NEW)** The lithographic ink of claim 34 wherein the ink is printed on a flexible polymer sheet.

43. (NEW) The lithographic ink of claim 34 wherein:
- a. the ink is printed on a substrate, with the ink having a thickness of less than about 5 microns;
  - b. a first electrically conducting layer is situated atop the ink, with the electrically conducting layer having a thickness of less than about 4 microns.
44. (NEW) The lithographic ink of claim 43 wherein the substrate is a flexible polymer sheet.
45. (NEW) The lithographic ink of claim 44 wherein an electrical component is attached to the first electrically conducting layer by means of a conductive polymer adhesive.
46. (NEW) The lithographic ink of claim 44 further comprising a second electrically conducting layer electroplated atop the first electrically conducting layer.
47. (NEW) The lithographic ink of claim 46 wherein an electrical component is attached to the first or second electrically conducting layer by a conductive polymer adhesive.